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Figure 1

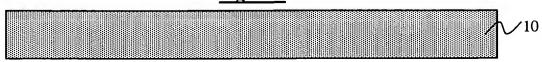


Figure 2

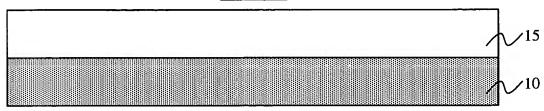
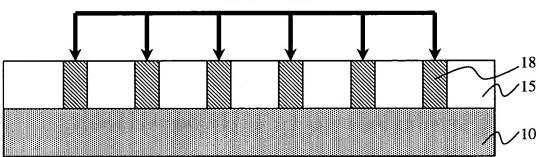


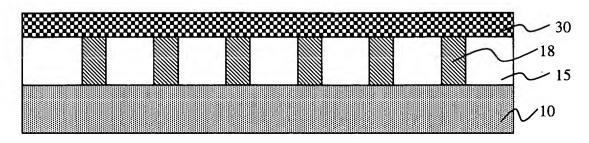
Figure 3

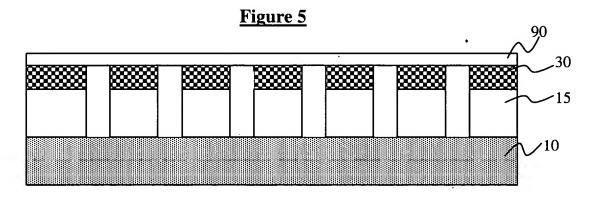




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Figure 4





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Figure 6

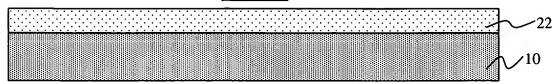


Figure 7

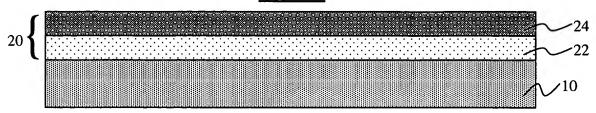
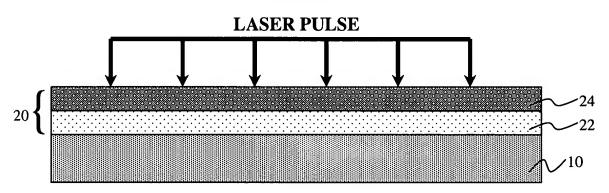
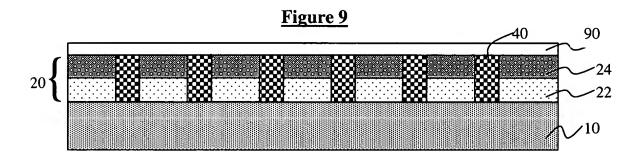


Figure 8





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Figure 10

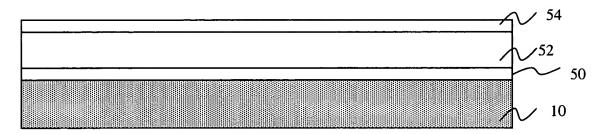


Figure 11

LASER PULSE

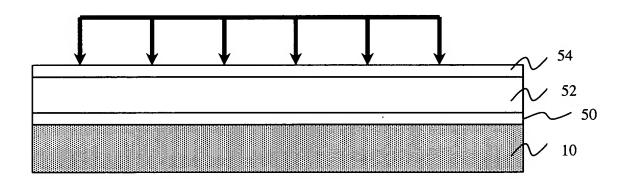
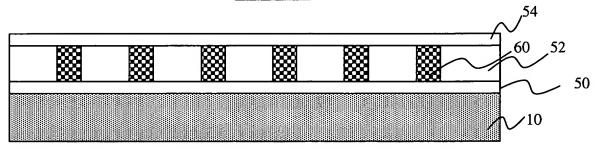


Figure 12



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Figure 13

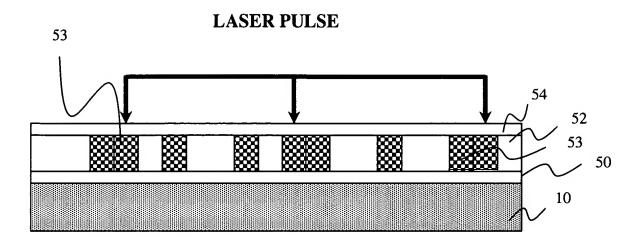


Figure 14

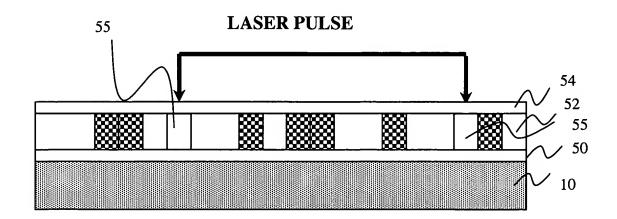


Figure 15

100 Applying photoresist to substrate

110 Positioning mask over photoresist and illuminating areas of photoresist through mask with light source 120 Removing mask and depositing magnetic material onto photoresist

130 Applying solvent to "lift off" exposed areas of photoresist and related portions of magnetic material

140 Applying protective layer to top surface to cover remaining magnetic material

Figure 16

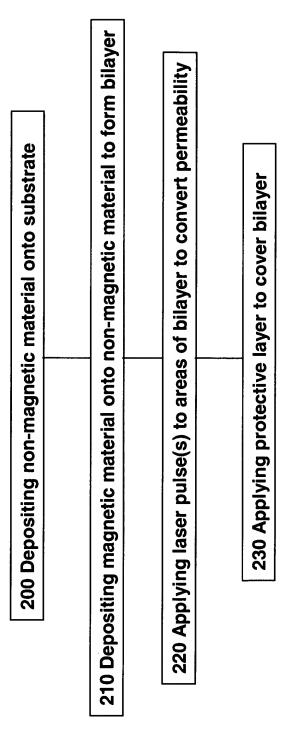


Figure 17

300 Applying layer of high thermally-conductive material onto substrate
310 Applying magnetic layer onto thermally-conductive material
320 Applying transparent protective layer onto magnetic layer
330 Applying heat pulses to areas of magnetic layer through transparent protective layer to alter magnetic permeability of those areas
340 Rewriting the medium by either applying slowly turning off heat pulses to convert high permeability regions to low
permeability regions and/or rapidly turning off heat pulses to convert low permeability regions to high permeability regions